

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) In the fabrication of a device, a method of patterning a device layer comprising:
providing a substrate comprising the device layer on its surface; and
patterning the device layer by pressing a stamp comprising a pattern against the substrate and the device layer, wherein the pattern includes protrusions on a surface of the stamp, the protrusions having a height greater than a thickness of the device layer, wherein the protrusions directly patterning pattern the device layer;
wherein the patterned device layer is a part of the fabricated device.
2. (Currently Amended) In the fabrication of a device, a method of patterning a device layer comprising:
providing a substrate comprising the device layer on its surface; and
patterning the device layer by pressing a stamp comprising a pattern against the substrate, wherein the pattern includes protrusions on a surface of the stamp, the protrusions having a height that is greater than a thickness of the device layer;
wherein the device comprises an organic LED device.
3. (Original) The method of claim 2 wherein the substrate comprises a polymeric substrate.
4. (Original) The method of claim 3 wherein the substrate comprises a flexible or ductile substrate.
5. (Currently Amended) The A method of patterning a device, comprising:~~of claim 4~~

~~wherein the~~

providing substrate comprises a transparent substrate, wherein the substrate has a device layer on its surface; and

patterning the device layer by pressing a stamp comprising a pattern against the substrate, wherein the pattern includes protrusions on a surface of the stamp, the protrusions having a height that is greater than a thickness of the device layer;

wherein the device comprises an organic LED device.

6. (Original) The method of claim 5 wherein the device layer comprises a transparent conductive layer.

7. (Original) The method of claim 6 wherein the transparent conductive layer comprises a conductive oxide.

8. (Currently Amended) The method of claim ~~wherein~~ 7 wherein the conductive oxide comprises indium-tin-oxide.

9. (Cancelled)

10. (Currently Amended) The method of claim ~~98~~ wherein patterning the device layer forms lower electrodes on the substrate.

11. (Cancelled)

12. (Currently Amended) The method of claim ~~11~~10 wherein the height of the protrusions is at least about 2-10 times greater than the thickness of the device layer.

13. (Currently Amended) The method of claim 12 wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in non-patterned areas.
14. (Currently Amended) The method of claim 13 wherein the load comprises a net pressure of greater than about 1.1[[θ]] times a yield strength of the substrate.
15. (Currently Amended) The method of claim 14 further ~~comprises~~ comprising processing to form OLED pixels.
16. (Currently Amended) The method of claim 15 wherein the processing to form OLED pixels comprises:
 - forming at least one organic functional layer on the lower electrodes; and
 - forming upper electrodes on the organic functional layer, wherein the OLED pixels are formed where the upper and lower electrodes sandwich the organic functional layer.
17. (Original) The method of claim 3 wherein the substrate comprises a transparent substrate.
18. (Original) The method of claim 17 wherein the device layer comprises a transparent conductive layer.
19. (Cancelled)
20. (Currently Amended) The method of claim ~~19~~18 wherein patterning the device layer forms lower electrodes on the substrate.
21. (Cancelled)

22. (Currently Amended) The method of claim ~~21~~20 wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in non-patterned areas.
23. (Currently Amended) The method of claim 22 further ~~comprises~~ comprising processing to form OLED pixels.
24. (Currently Amended) The method of claim 23 wherein the processing to form OLED pixels comprises:
forming at least one organic functional layer on the lower electrodes; and
forming upper electrodes on the organic functional layer, wherein the OLED pixels are formed where the upper and lower electrodes sandwich the organic functional layer.
25. (Original) The method of claim 3 wherein the device layer comprises a conductive layer.
26. (Cancelled)
27. (Currently Amended) ~~The~~ A method of patterning a device layer, comprising:
providing a polymeric substrate comprising a device layer on its surface, wherein the device layer comprises a conductive layer; and
~~claim 26 wherein~~ patterning the device layer by pressing a stamp comprising a pattern against the substrate, wherein the pattern includes protrusions on a surface of the stamp, the protrusions having a height that is greater than a thickness of the device layer, wherein the patterning forms lower electrodes on the substrate;
wherein the device comprises an organic LED device.
28. (Cancelled)

29. (Currently Amended) The method of claim ~~28~~27, wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in non-patterned areas.

30. (Currently Amended) The method of claim 29 further ~~comprises~~ comprising processing to form OLED pixels.

31. (Currently Amended) The method of claim 30 wherein the processing to form OLED pixels comprises:

forming at least one organic functional layer on the lower electrodes; and
forming upper electrodes on the organic functional layer, wherein the OLED pixels are formed where the upper and lower electrodes sandwich the organic functional layer.

32. (Original) The method of claim 2 wherein the substrate comprises a material selected from the group consisting of polyester, poly(ethylene terephthalate), poly(butylene terephthalate), poly(ethylene naphthalate), polyethyleneterephthalate, polycarbonate, polyimides, polysulfones, poly(p-phenylene ether sulfone), polyethylene, polypropylene, poly(vinyl chloride), polystyrene, and poly(methyl methacrylate).

33. (Original) The method of claim 32 wherein the device layer comprises a conductive layer.

34. (Currently Amended) The method of claim 33 wherein ~~the pattern is produced by protrusions on a surface of the stamp~~, the pattern is used to form lower electrodes on the substrate.

35. (Cancelled)

36. (Currently Amended) The method of claim ~~35~~ 34, wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in non-patterned areas.

37. (Currently Amended) The method of claim 36 further ~~comprises~~ comprising processing to form OLED pixels, the method further comprising:

forming at least one organic functional layer on the lower electrodes; and

forming upper electrodes on the organic functional layer, wherein OLED pixels are formed where the upper and lower electrodes sandwich the organic functional layer.

38. (Original) The method of claim 1 wherein the substrate comprises a polymeric substrate.

39. (Cancelled)

40. (Cancelled)

41. (Currently Amended) The method of claim ~~40~~38 wherein the height of the protrusions is at least about 5-10 times greater than the thickness of the device layer.

42. (Currently Amended) The method of claim 41 wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in non-patterned areas.

43. (Original) The method of claim 42 wherein the load comprises a net pressure of greater than about 1.1 times a yield strength of the substrate.

44. (Currently Amended) The method of claim 43 further ~~comprises~~ comprising processing to form the device.

45. (Original) The method of claim 44 wherein the device comprises a device selected from the group consisting of an electrical device, a mechanical device, a electromechanical device, and a microelectromechanical system.

46. (Currently Amended) The method of claim ~~40~~38 wherein the stamp is pressed against the substrate surface under a load without causing the device layer to crack in non-patterned areas.

47. (Original) The method of claim 46 further comprises processing to form the device.

48. (Original) The method of claim 47 wherein the device comprises a device selected from the group consisting of an electrical device, a mechanical device, a electromechanical device, and a microelectromechanical system.

49. (Original) The method of claim 1 wherein the substrate comprises a material selected from the group consisting of polyester, poly(ethylene terephthalate), poly(butylene terephthalate), poly(enthylene naphthalate), polyethylenesteraphthalate, polycarbonate, polyimides, polysulfones, poly(p-phenylene ether sulfone), polyethylene, polypropylene, poly(vinyl chloride), polystyrene, and poly(methyl methyleacrylate).

50. (Cancelled)

51. (Cancelled)

52. (Currently Amended) The method of claim ~~51~~ 49 wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in non-patterned areas.

53. (Currently Amended) The method of claim 52 further ~~comprises~~ comprising processing to form the device.

54. (Previously Presented) A method of patterning a device layer in the fabrication of a device, comprising:

rotating a stamp comprising a drum with a pattern; and
translating a substrate with a device layer thereon as the stamp is rotated to directly pattern the device layer;
wherein the patterned device layer is a part of the fabricated device.

55. (Previously Presented) The method of claim 54 wherein the substrate comprises a polymeric substrate.

56. (Original) The method of claim 55 wherein the pattern is produced by protrusions on a surface of the stamp.

57. (Original) The method of claim 56 wherein the protrusions comprise a height greater than a thickness of the device layer to pattern the device layer.

58. (Currently Amended) The method of claim 57 wherein the stamp is pressed against the substrate ~~surface~~ under a load without causing the device layer to crack in on non-patterned areas.

59. (Currently Amended) The method of claim 58 further ~~comprises~~ comprising processing to form the device.

60. (Original) The method of claim 59 wherein the device comprises a device selected from the group consisting of an electrical device, a mechanical device, a electromechanical device,

and a microelectromechanical system.

61. (Original) The method of claim 59 wherein the device comprises an OLED device.

62. (New) The method of claim 54, wherein:

translating a substrate includes separating the device layer into a first portion and a second portion;

the first portion contacts protruding portions of the pattern during the step of translating the substrate; and

the first portion does not contact the second portion after the step of translating the substrate.

63. (New) The method of claim 1, wherein:

patterning the device layer includes separating the device layer into a first portion and a second portion;

the first portion contacts protrusions of the pattern during the step of patterning the device layer; and

the first portion does not contact the second portion after the step of patterning the device layer.

64. (New) The method of claim 2, wherein:

patterning the device layer includes separating the device layer into a first portion and a second portion;

the first portion contacts the protrusions of the pattern during the step of patterning the device layer; and

the first portion does not contact the second portion after the step of patterning the device layer.